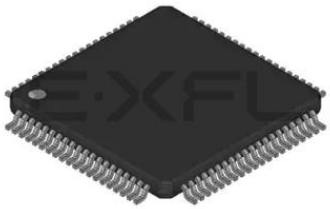
Infineon Technologies - XC2387E104F128LAAKFUMA1 Datasheet



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Applications of "Embedded - Microcontrollers"

Details	
Product Status	Obsolete
Core Processor	C166SV2
Core Size	16/32-Bit
Speed	128MHz
Connectivity	CANbus, EBI/EMI, FlexRay, I²C, LINbus, SPI, UART/USART
Peripherals	I²S, POR, PWM, WDT
Number of I/O	118
Program Memory Size	832KB (832K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	98K x 8
Voltage - Supply (Vcc/Vdd)	3V ~ 5.5V
Data Converters	A/D 24x12b
Oscillator Type	External
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Surface Mount
Package / Case	144-LQFP Exposed Pad
Supplier Device Package	PG-LQFP-144-4
Purchase URL	https://www.e-xfl.com/product-detail/infineon-technologies/xc2387e104f128laakfuma1

2.1 Pin Configuration and Definition

The pins of the XC238xA are described in detail in **Table 6**, which includes all alternate functions. For further explanations please refer to the footnotes at the end of the table. The following figure summarizes all pins, showing their locations on the four sides of the package.

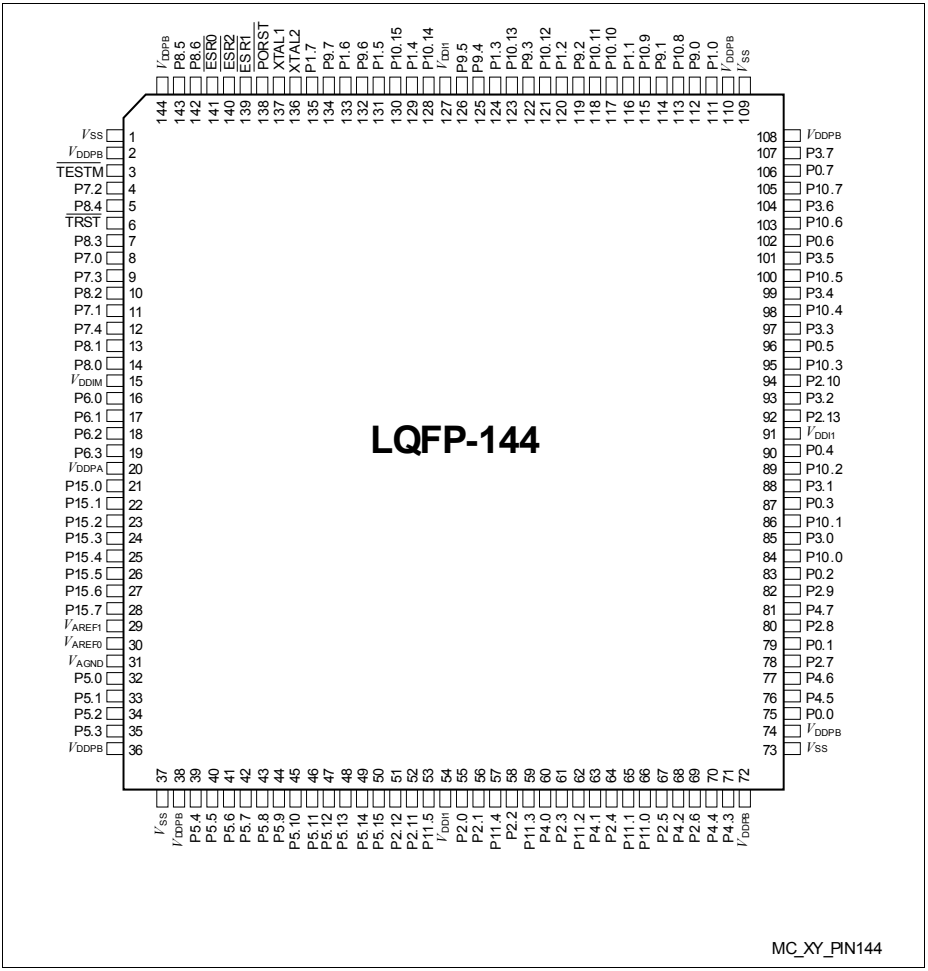

Figure 3 XC238xA Pin Configuration (top view)

Table 6 Pin Definitions and Functions (cont'd)

Pin	Symbol	Ctrl.	Type	Function
12	P7.4	O0 / I	St/B	**Bit 4 of Port 7, General Purpose Input/Output**
	EMUX2	O1	St/B	**External Analog MUX Control Output 2 (ADC1)**
	U0C1_DOUT	O2	St/B	**USIC0 Channel 1 Shift Data Output**
	U0C1_SCLKOUT	O3	St/B	**USIC0 Channel 1 Shift Clock Output**
	CCU62_CCPOS2A	I	St/B	**CCU62 Position Input 2**
	TCK_C	IH	St/B	**DAP0/JTAG Clock Input** If JTAG pos. C is selected during start-up, an internal pull-up device will hold this pin high when nothing is driving it. If DAP pos. 2 is selected during start-up, an internal pull-down device will hold this pin low when nothing is driving it.
	U0C0_DX0D	I	St/B	**USIC0 Channel 0 Shift Data Input**
	U0C1_DX1E	I	St/B	**USIC0 Channel 1 Shift Clock Input**
13	P8.1	O0 / I	St/B	**Bit 1 of Port 8, General Purpose Input/Output**
	CCU60_CC61	O1	St/B	**CCU60 Channel 1 Output**
	CCU60_CC61INB	I	St/B	**CCU60 Channel 1 Input**
	RxDC1F	I	St/B	**CAN Node 1 Receive Data Input**
14	P8.0	O0 / I	St/B	**Bit 0 of Port 8, General Purpose Input/Output**
	CCU60_CC60	O1	St/B	**CCU60 Channel 0 Output**
	CCU60_CC60INB	I	St/B	**CCU60 Channel 0 Input**
16	P6.0	O0 / I	DA/A	**Bit 0 of Port 6, General Purpose Input/Output**
	EMUX0	O1	DA/A	**External Analog MUX Control Output 0 (ADC0)**
	TxDC2	O2	DA/A	**CAN Node 2 Transmit Data Output**
	$\overline{\text{BRKOUT}}$	O3	DA/A	**OCDS Break Signal Output**
	ADCx_REQGTyG	I	DA/A	**External Request Gate Input for ADC0/1**
	U1C1_DX0E	I	DA/A	**USIC1 Channel 1 Shift Data Input**

Table 6 Pin Definitions and Functions (cont'd)

Pin	Symbol	Ctrl.	Type	Function
56	P2.1	O0 / I	St/B	**Bit 1 of Port 2, General Purpose Input/Output**
	TxDC0	O1	St/B	**CAN Node 0 Transmit Data Output**
	CCU63_CC61	O2	St/B	**CCU63 Channel 1 Output**
	AD14	OH / IH	St/B	**External Bus Interface Address/Data Line 14**
	CCU63_CC61INB	I	St/B	**CCU63 Channel 1 Input**
	T5EUDB	I	St/B	**GPT12E Timer T5 External Up/Down Control Input**
	ESR1_5	I	St/B	**ESR1 Trigger Input 5**
57	P11.4	O0 / I	St/B	**Bit 4 of Port 11, General Purpose Input/Output**
	CCU61_CC62	O1	St/B	**CCU61 Channel 2 Output**
	CCU61_CC62INB	I	St/B	**CCU61 Channel 2 Input**
58	P2.2	O0 / I	St/B	**Bit 2 of Port 2, General Purpose Input/Output**
	TxDC1	O1	St/B	**CAN Node 1 Transmit Data Output**
	CCU63_CC62	O2	St/B	**CCU63 Channel 2 Output**
	AD15	OH / IH	St/B	**External Bus Interface Address/Data Line 15**
	CCU63_CC62INB	I	St/B	**CCU63 Channel 2 Input**
	ESR2_5	I	St/B	**ESR2 Trigger Input 5**
59	P11.3	O0 / I	St/B	**Bit 3 of Port 11, General Purpose Input/Output**
	CCU61_COUT63	O1	St/B	**CCU61 Channel 3 Output**
	CCU61_COUT62	O2	St/B	**CCU61 Channel 2 Output**
	CCU61_T13HRF	I	St/B	**External Run Control Input for T13 of CCU61**

Table 6 Pin Definitions and Functions (cont'd)

Pin	Symbol	Ctrl.	Type	Function
82	P2.9	O0 / I	St/B	**Bit 9 of Port 2, General Purpose Input/Output**
	U0C1_DOUT	O1	St/B	**USIC0 Channel 1 Shift Data Output**
	TxDC1	O2	St/B	**CAN Node 1 Transmit Data Output**
	CC2_CC22	O3 / I	St/B	**CAPCOM2 CC22IO Capture Inp./ Compare Out.**
	A22	OH	St/B	**External Bus Interface Address Line 22**
	CLKIN1	I	St/B	**Clock Signal Input 1**
	TCK_A	IH	St/B	**DAP0/JTAG Clock Input** If JTAG pos. A is selected during start-up, an internal pull-up device will hold this pin high when nothing is driving it. If DAP pos. 0 is selected during start-up, an internal pull-down device will hold this pin low when nothing is driving it.
83	P0.2	O0 / I	St/B	**Bit 2 of Port 0, General Purpose Input/Output**
	U1C0_SCLKOUT	O1	St/B	**USIC1 Channel 0 Shift Clock Output**
	TxDC0	O2	St/B	**CAN Node 0 Transmit Data Output**
	CCU61_CC62	O3	St/B	**CCU61 Channel 2 Output**
	A2	OH	St/B	**External Bus Interface Address Line 2**
	U1C0_DX1B	I	St/B	**USIC1 Channel 0 Shift Clock Input**
	CCU61_CC62INA	I	St/B	**CCU61 Channel 2 Input**

Table 6 Pin Definitions and Functions (cont'd)

Pin	Symbol	Ctrl.	Type	Function
84	P10.0	O0 / I	St/B	**Bit 0 of Port 10, General Purpose Input/Output**
	U0C1_DOUT	O1	St/B	**USIC0 Channel 1 Shift Data Output**
	CCU60_CC60	O2	St/B	**CCU60 Channel 0 Output**
	AD0	OH / IH	St/B	**External Bus Interface Address/Data Line 0**
	CCU60_CC60INA	I	St/B	**CCU60 Channel 0 Input**
	ESR1_2	I	St/B	**ESR1 Trigger Input 2**
	U0C0_DX0A	I	St/B	**USIC0 Channel 0 Shift Data Input**
	U0C1_DX0A	I	St/B	**USIC0 Channel 1 Shift Data Input**
85	P3.0	O0 / I	St/B	**Bit 0 of Port 3, General Purpose Input/Output**
	U2C0_DOUT	O1	St/B	**USIC2 Channel 0 Shift Data Output**
	$\overline{\text{BREQ}}$	OH	St/B	**External Bus Request Output**
	ESR1_1	I	St/B	**ESR1 Trigger Input 1**
	U2C0_DX0A	I	St/B	**USIC2 Channel 0 Shift Data Input**
	U2C0_DX1A	I	St/B	**USIC2 Channel 0 Shift Clock Input**
86	P10.1	O0 / I	St/B	**Bit 1 of Port 10, General Purpose Input/Output**
	U0C0_DOUT	O1	St/B	**USIC0 Channel 0 Shift Data Output**
	CCU60_CC61	O2	St/B	**CCU60 Channel 1 Output**
	AD1	OH / IH	St/B	**External Bus Interface Address/Data Line 1**
	CCU60_CC61INA	I	St/B	**CCU60 Channel 1 Input**
	U0C0_DX1A	I	St/B	**USIC0 Channel 0 Shift Clock Input**
	U0C0_DX0B	I	St/B	**USIC0 Channel 0 Shift Data Input**

Table 6 Pin Definitions and Functions (cont'd)

Pin	Symbol	Ctrl.	Type	Function
99	P3.4	O0 / I	St/B	**Bit 4 of Port 3, General Purpose Input/Output**
	U2C1_SELO 0	O1	St/B	**USIC2 Channel 1 Select/Control 0 Output**
	U2C0_SELO 1	O2	St/B	**USIC2 Channel 0 Select/Control 1 Output**
	U0C0_SELO 4	O3	St/B	**USIC0 Channel 0 Select/Control 4 Output**
	U2C1_DX2A	I	St/B	**USIC2 Channel 1 Shift Control Input**
100	P10.5	O0 / I	St/B	**Bit 5 of Port 10, General Purpose Input/Output**
	U0C1_SCLK OUT	O1	St/B	**USIC0 Channel 1 Shift Clock Output**
	CCU60_COU T62	O2	St/B	**CCU60 Channel 2 Output**
	U2C0_DOUT	O3	St/B	**USIC2 Channel 0 Shift Data Output**
	AD5	OH / IH	St/B	**External Bus Interface Address/Data Line 5**
	U0C1_DX1B	I	St/B	**USIC0 Channel 1 Shift Clock Input**
101	P3.5	O0 / I	St/B	**Bit 5 of Port 3, General Purpose Input/Output**
	U2C1_SCLK OUT	O1	St/B	**USIC2 Channel 1 Shift Clock Output**
	U2C0_SELO 2	O2	St/B	**USIC2 Channel 0 Select/Control 2 Output**
	U0C0_SELO 5	O3	St/B	**USIC0 Channel 0 Select/Control 5 Output**
	U2C1_DX1A	I	St/B	**USIC2 Channel 1 Shift Clock Input**

Table 6 Pin Definitions and Functions (cont'd)

Pin	Symbol	Ctrl.	Type	Function
105	P10.7	O0 / I	St/B	**Bit 7 of Port 10, General Purpose Input/Output**
	U0C1_DOUT	O1	St/B	**USIC0 Channel 1 Shift Data Output**
	CCU60_COUT63	O2	St/B	**CCU60 Channel 3 Output**
	AD7	OH / IH	St/B	**External Bus Interface Address/Data Line 7**
	U0C1_DX0B	I	St/B	**USIC0 Channel 1 Shift Data Input**
	CCU60_CCPOS0A	I	St/B	**CCU60 Position Input 0**
	T4INB	I	St/B	**GPT12E Timer T4 Count/Gate Input**
106	P0.7	O0 / I	St/B	**Bit 7 of Port 0, General Purpose Input/Output**
	U1C1_DOUT	O1	St/B	**USIC1 Channel 1 Shift Data Output**
	U1C0_SELO3	O2	St/B	**USIC1 Channel 0 Select/Control 3 Output**
	A7	OH	St/B	**External Bus Interface Address Line 7**
	U1C1_DX0B	I	St/B	**USIC1 Channel 1 Shift Data Input**
	CCU61_CTRAPB	I	St/B	**CCU61 Emergency Trap Input**
107	P3.7	O0 / I	St/B	**Bit 7 of Port 3, General Purpose Input/Output**
	U2C1_DOUT	O1	St/B	**USIC2 Channel 1 Shift Data Output**
	U2C0_SELO3	O2	St/B	**USIC2 Channel 0 Select/Control 3 Output**
	U0C0_SELO7	O3	St/B	**USIC0 Channel 0 Select/Control 7 Output**
	U2C1_DX0B	I	St/B	**USIC2 Channel 1 Shift Data Input**

Table 6 Pin Definitions and Functions (cont'd)

Pin	Symbol	Ctrl.	Type	Function
141	$\overline{\text{ESR0}}$	O0 / I	St/B	**External Service Request 0** After power-up, $\overline{\text{ESR0}}$ operates as open-drain bidirectional reset with a weak pull-up.
	U1C0_DX0E	I	St/B	**USIC1 Channel 0 Shift Data Input**
	U1C0_DX2B	I	St/B	**USIC1 Channel 0 Shift Control Input**
142	P8.6	O0 / I	St/B	**Bit 6 of Port 8, General Purpose Input/Output**
	CCU60_COUT63	O1	St/B	**CCU60 Channel 3 Output**
	MCHK_MATCH	O3	St/B	**Memory Checker Match Output**
	CCU60_CTRAPB	I	St/B	**CCU60 Emergency Trap Input**
	$\overline{\text{BRKIN\_D}}$	I	St/B	**OCDS Break Signal Input**
	CCU62_CTRAPD	I	St/B	**CCU62 Emergency Trap Input**
143	P8.5	O0 / I	St/B	**Bit 5 of Port 8, General Purpose Input/Output**
	CCU60_COUT62	O1	St/B	**CCU60 Channel 2 Output**
	CCU62_CC62	O2	St/B	**CCU62 Channel 2 Output**
	TCK_D	IH	St/B	**DAP0/JTAG Clock Input** If JTAG pos. D is selected during start-up, an internal pull-up device will hold this pin high when nothing is driving it.
	CCU62_CC62INB	I	St/B	**CCU62 Channel 2 Input**
15	V_{DDIM}	-	PS/M	**Digital Core Supply Voltage for Domain M** Decouple with a ceramic capacitor, see Data Sheet for details.
54, 91, 127	V_{DDI1}	-	PS/1	**Digital Core Supply Voltage for Domain 1** Decouple with a ceramic capacitor, see Data Sheet for details. All V_{DDI1} pins must be connected to each other.

Table 6 Pin Definitions and Functions (cont'd)

Pin	Symbol	Ctrl.	Type	Function
20	V_{DDPA}	-	PS/A	**Digital Pad Supply Voltage for Domain A** Connect decoupling capacitors to adjacent V_{DDP}/V_{SS} pin pairs as close as possible to the pins. *Note: The A/D_Converters and ports P5, P6 and P15 are fed from supply voltage V_{DDPA}.*
2, 36, 38, 72, 74, 108, 110, 144	V_{DDPB}	-	PS/B	**Digital Pad Supply Voltage for Domain B** Connect decoupling capacitors to adjacent V_{DDP}/V_{SS} pin pairs as close as possible to the pins. *Note: The on-chip voltage regulators and all ports except P5, P6 and P15 are fed from supply voltage V_{DDPB}.*
1, 37, 73, 109	V_{SS}	-	PS/--	**Digital Ground** All V_{SS} pins must be connected to the ground-line or ground-plane. *Note: Also the exposed pad is connected internally to V_{SS}. To improve the EMC behavior, it is recommended to connect the exposed pad to the board ground. For thermal aspects, please refer to the Data Sheet. Board layout examples are given in an application note.*

1) To generate the reference clock output for bus timing measurement, f_{SYS} must be selected as source for EXTCLK and P2.8 must be selected as output pin. Also the high-speed clock pad must be enabled. This configuration is referred to as reference clock output signal CLKOUT.

3.1 Memory Subsystem and Organization

The memory space of the XC238xA is configured in the von Neumann architecture. In this architecture all internal and external resources, including code memory, data memory, registers and I/O ports, are organized in the same linear address space.

Table 8 XC238xA Memory Map [1)]

Address Area	Start Loc.	End Loc.	Area Size[2)]	Notes
IMB register space	$FF'FF00_H$	$FF'FFFF_H$	256 Bytes	–
Reserved (Access trap)	$F0'0000_H$	$FF'FEFF_H$	<1 Mbyte	Minus IMB registers
Reserved for EPSRAM	$E8'8000_H$	$EF'FFFF_H$	480 Kbytes	Mirrors EPSRAM
Emulated PSRAM	$E8'0000_H$	$E8'7FFF_H$	32 Kbytes	With Flash timing
Reserved for PSRAM	$E0'8000_H$	$E7'FFFF_H$	480 Kbytes	Mirrors PSRAM
Program SRAM	$E0'0000_H$	$E0'7FFF_H$	32 Kbytes	Maximum speed
Reserved for Flash	$CD'0000_H$	$DF'FFFF_H$	<1.25 Mbytes	–
Program Flash 3	$CC'0000_H$	$CC'FFFF_H$	64 Kbytes	–
Program Flash 2	$C8'0000_H$	$CB'FFFF_H$	256 Kbytes	–
Program Flash 1	$C4'0000_H$	$C7'FFFF_H$	256 Kbytes	–
Program Flash 0	$C0'0000_H$	$C3'FFFF_H$	256 Kbytes	[3)]
External memory area	$40'0000_H$	$BF'FFFF_H$	8 Mbytes	–
Available Ext. IO area[4)]	$21'0000_H$	$3F'FFFF_H$	< 2 Mbytes	Minus USIC/CAN
Reserved	$20'BC00_H$	$20'FFFF_H$	17 Kbytes	–
USIC alternate regs.	$20'B000_H$	$20'BFFF_H$	4 Kbytes	Accessed via EBC
MultiCAN alternate regs.	$20'8000_H$	$20'AFFF_H$	12 Kbytes	Accessed via EBC
Reserved	$20'6000_H$	$20'7FFF_H$	8 Kbytes	–
USIC registers	$20'4000_H$	$20'5FFF_H$	8 Kbytes	Accessed via EBC
MultiCAN registers	$20'0000_H$	$20'3FFF_H$	16 Kbytes	Accessed via EBC
External memory area	$01'0000_H$	$1F'FFFF_H$	< 2 Mbytes	Minus segment 0
SFR area	$00'FE00_H$	$00'FFFF_H$	0.5 Kbyte	–
Dual-Port RAM	$00'F600_H$	$00'FDFF_H$	2 Kbytes	–
Reserved for DPRAM	$00'F200_H$	$00'F5FF_H$	1 Kbyte	–
ESFR area	$00'F000_H$	$00'F1FF_H$	0.5 Kbyte	–
XSFR area	$00'E000_H$	$00'EFFF_H$	4 Kbytes	–

to a dedicated vector table location). The occurrence of a hardware trap is also indicated by a single bit in the trap flag register (TFR). Unless another higher-priority trap service is in progress, a hardware trap will interrupt any ongoing program execution. In turn, hardware trap services can normally not be interrupted by standard or PEC interrupts.

Depending on the package option up to 3 External Service Request (ESR) pins are provided. The ESR unit processes their input values and allows to implement user controlled trap functions (System Requests SR0 and SR1). In this way reset, wakeup and power control can be efficiently realized.

Software interrupts are supported by the 'TRAP' instruction in combination with an individual trap (interrupt) number. Alternatively to emulate an interrupt by software a program can trigger interrupt requests by writing the Interrupt Request (IR) bit of an interrupt control register.

3.7 On-Chip Debug Support (OCDS)

The On-Chip Debug Support system built into the XC238xA provides a broad range of debug and emulation features. User software running on the XC238xA can be debugged within the target system environment.

The OCDS is controlled by an external debugging device via the debug interface. This either consists of the 2-pin Device Access Port (DAP) or of the JTAG port conforming to IEEE-1149. The debug interface can be completed with an optional break interface.

The debugger controls the OCDS with a set of dedicated registers accessible via the debug interface (DAP or JTAG). In addition the OCDS system can be controlled by the CPU, e.g. by a monitor program. An injection interface allows the execution of OCDS-generated instructions by the CPU.

Multiple breakpoints can be triggered by on-chip hardware, by software, or by an external trigger input. Single stepping is supported, as is the injection of arbitrary instructions and read/write access to the complete internal address space. A breakpoint trigger can be answered with a CPU halt, a monitor call, a data transfer, or/and the activation of an external signal.

Tracing data can be obtained via the debug interface, or via the external bus interface for increased performance.

Tracing of program execution is supported by the XC2000 Family emulation device.

The DAP interface uses two interface signals, the JTAG interface uses four interface signals, to communicate with external circuitry. The debug interface can be amended with two optional break lines.

3.10 General Purpose Timer (GPT12E) Unit

The GPT12E unit is a very flexible multifunctional timer/counter structure which can be used for many different timing tasks such as event timing and counting, pulse width and duty cycle measurements, pulse generation, or pulse multiplication.

The GPT12E unit incorporates five 16-bit timers organized in two separate modules, GPT1 and GPT2. Each timer in each module may either operate independently in a number of different modes or be concatenated with another timer of the same module.

Each of the three timers T2, T3, T4 of **module GPT1** can be configured individually for one of four basic modes of operation: Timer, Gated Timer, Counter, and Incremental Interface Mode. In Timer Mode, the input clock for a timer is derived from the system clock and divided by a programmable prescaler. Counter Mode allows timer clocking in reference to external events.

Pulse width or duty cycle measurement is supported in Gated Timer Mode, where the operation of a timer is controlled by the ‘gate’ level on an external input pin. For these purposes each timer has one associated port pin (TxIN) which serves as a gate or clock input. The maximum resolution of the timers in module GPT1 is 4 system clock cycles.

The counting direction (up/down) for each timer can be programmed by software or altered dynamically by an external signal on a port pin (TxEUD), e.g. to facilitate position tracking.

In Incremental Interface Mode the GPT1 timers can be directly connected to the incremental position sensor signals A and B through their respective inputs TxIN and TxEUD. Direction and counting signals are internally derived from these two input signals, so that the contents of the respective timer Tx corresponds to the sensor position. The third position sensor signal TOP0 can be connected to an interrupt input.

Timer T3 has an output toggle latch (T3OTL) which changes its state on each timer overflow/underflow. The state of this latch may be output on pin T3OUT e.g. for time out monitoring of external hardware components. It may also be used internally to clock timers T2 and T4 for measuring long time periods with high resolution.

In addition to the basic operating modes, T2 and T4 may be configured as reload or capture register for timer T3. A timer used as capture or reload register is stopped. The contents of timer T3 is captured into T2 or T4 in response to a signal at the associated input pin (TxIN). Timer T3 is reloaded with the contents of T2 or T4, triggered either by an external signal or a selectable state transition of its toggle latch T3OTL. When both T2 and T4 are configured to alternately reload T3 on opposite state transitions of T3OTL with the low and high times of a PWM signal, this signal can be continuously generated without software intervention.

4.2.1 DC Parameters

Keeping signal levels within the limits specified in this table ensures operation without overload conditions. For signal levels outside these specifications, also refer to the specification of the overload current I_{OV}.

Note: Operating Conditions apply.

Table 14 is valid under the following conditions:
$V_{DDP} \geq 4.5$ V; $V_{DDPtyp} = 5$ V; $V_{DDP} \leq 5.5$ V

Table 14 DC Characteristics for Upper Voltage Range

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Pin capacitance (digital inputs/outputs). To be doubled for double bond pins.[1]	C_{IO} CC	–	–	10	pF	not subject to production test
Input Hysteresis[2]	HYS CC	0.11 x V_{DDP}	–	–	V	R_S = 0 Ohm
Absolute input leakage current on pins of analog ports[3]	$\|I_{OZ1}\|$ CC	–	10	200	nA	$V_{IN} > 0$ V; $V_{IN} < V_{DDP}$
Absolute input leakage current for all other pins. To be doubled for double bond pins.[3][1][4]	$\|I_{OZ2}\|$ CC	–	0.2	5	µA	$T_J \leq 110$ °C; $V_{IN} < V_{DDP}$; $V_{IN} > V_{SS}$
		–	0.2	15	µA	$T_J \leq 150$ °C; $V_{IN} < V_{DDP}$; $V_{IN} > V_{SS}$
Pull Level Force Current[5]	$\|I_{PLF}\|$ SR	250	–	–	µA	[6]
Pull Level Keep Current[7]	$\|I_{PLK}\|$ SR	–	–	30	µA	[6]
Input high voltage (all except XTAL1)	V_{IH} SR	0.7 x V_{DDP}	–	V_{DDP} + 0.3	V	
Input low voltage (all except XTAL1)	V_{IL} SR	-0.3	–	0.3 x V_{DDP}	V	
Output High voltage[8]	V_{OH} CC	V_{DDP} - 1.0	–	–	V	$I_{OH} \geq I_{OHmax}$
		V_{DDP} - 0.4	–	–	V	$I_{OH} \geq I_{OHnom}$[9]

4.2.3 Power Consumption

The power consumed by the XC238xA depends on several factors such as supply voltage, operating frequency, active circuits, and operating temperature. The power consumption specified here consists of two components:

- The switching current I_S depends on the device activity
- The leakage current I_{LK} depends on the device temperature

To determine the actual power consumption, always both components, switching current I_S and leakage current I_{LK} must be added:

$I_{DDP} = I_S + I_{LK}$.

Note: The power consumption values are not subject to production test. They are verified by design/characterization.
To determine the total power consumption for dimensioning the external power supply, also the pad driver currents must be considered.

The given power consumption parameters and their values refer to specific operating conditions:

- **Active mode**:
  Regular operation, i.e. peripherals are active, code execution out of Flash.
- **Stopover mode**:
  Crystal oscillator and PLL stopped, Flash switched off, clock in domain DMP_1 stopped.

Note: The maximum values cover the complete specified operating range of all manufactured devices.
The typical values refer to average devices under typical conditions, such as nominal supply voltage, room temperature, application-oriented activity.
After a power reset, the decoupling capacitors for V_{DDIM} and V_{DDI1} are charged with the maximum possible current.

For additional information, please refer to **Section 5.2, Thermal Considerations**.

Note: Operating Conditions apply.

Table 16 Switching Power Consumption

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Power supply current (active) with all peripherals active and EVVRs on	I_{SACT} CC	–	10 + 0.6 x f_{SYS} [1]	10 + 1.0 x f_{SYS} [1]	mA	2)3)
Power supply current in stopover mode, EVVRs on	I_{SSO} CC	–	0.7	2.0	mA	

1) f_{SYS} in MHz.

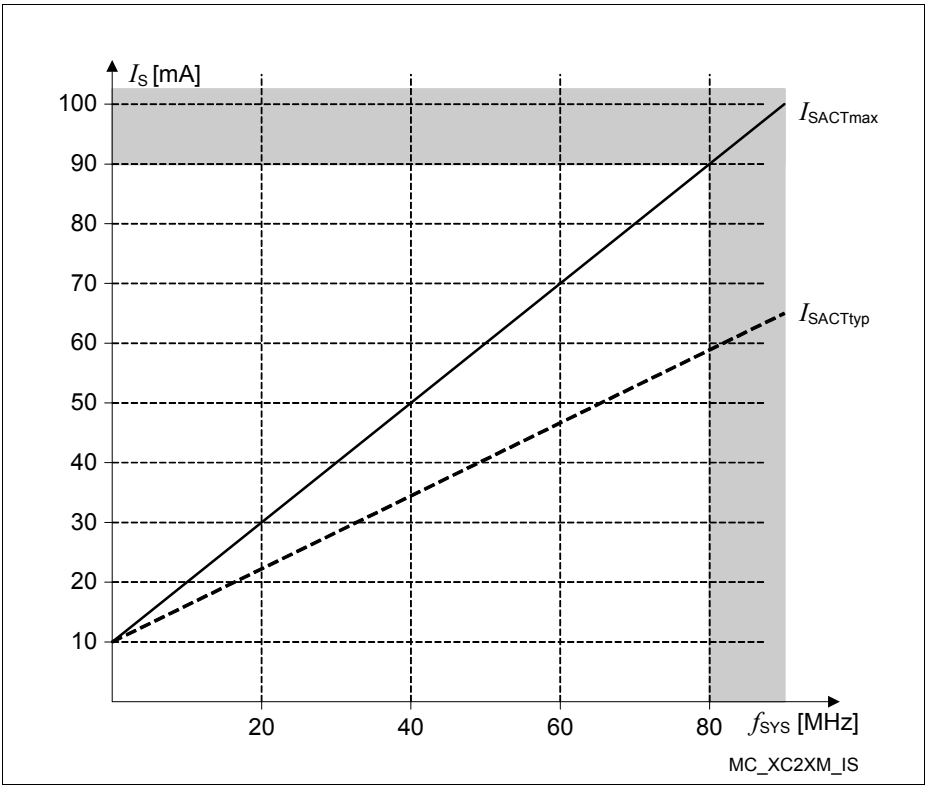

Figure 14 Supply Current in Active Mode as a Function of Frequency

Note: Operating Conditions apply.

Table 17 Leakage Power Consumption

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Leakage supply current (DMP_1 powered)[1]	I_{LK1} CC	–	0.03	0.05	mA	T_J= 25 °C[1]
		–	0.5	1.3	mA	T_J= 85 °C[1]
		–	2.1	6.2	mA	T_J= 125 °C[1]
		–	4.4	13.7	mA	T_J= 150 °C[1]

1) All inputs (including pins configured as inputs) are set at 0 V to 0.1 V or at V_{DDP} - 0.1 V to V_{DDP} and all outputs (including pins configured as outputs) are disconnected.

Note: A fraction of the leakage current flows through domain DMP_A (pin V_{DDPA}). This current can be calculated as 7 000 $\times e^{-\alpha}$, with α = 5 000 / (273 + 1.3$\times T_J$). For T_J = 150°C, this results in a current of 160 μA.

The leakage power consumption can be calculated according to the following formulas:

I_{LK0} = 500 000 × $e^{-\alpha}$, with α = 3 000 / (273 + B$\times T_J$)

Parameter B must be replaced by

- 1.0 for typical values
- 1.6 for maximum values

I_{LK1} = 600 000 × $e^{-\alpha}$, with α = 5 000 / (273 + B$\times T_J$)

Parameter B must be replaced by

- 1.0 for typical values
- 1.3 for maximum values

Table 21 Coding of bit fields LEVxV in Register SWDCON0 (cont'd)

Code	Default Voltage Level	Notes[1)]
1001_B	4.5 V	LEV2V: no request
1010_B	4.6 V	
1011_B	4.7 V	
1100_B	4.8 V	
1101_B	4.9 V	
1110_B	5.0 V	
1111_B	5.5 V	

1) The indicated default levels are selected automatically after a power reset.

Table 22 Coding of Bitfields LEVxV in Registers PVCyCONz

Code	Default Voltage Level	Notes[1)]
000_B	0.95 V	
001_B	1.05 V	
010_B	1.15 V	
011_B	1.25 V	
100_B	1.35 V	LEV1V: reset request
101_B	1.45 V	LEV2V: interrupt request[2)]
110_B	1.55 V	
111_B	1.65 V	

1) The indicated default levels are selected automatically after a power reset.

2) Due to variations of the tolerance of both the Embedded Voltage Regulators (EVR) and the PVC levels, this interrupt can be triggered inadvertently, even though the core voltage is within the normal range. It is, therefore, recommended not to use the this warning level.

The timing in the AC Characteristics refers to TCSs. Timing must be calculated using the minimum TCS possible under the given circumstances.
The actual minimum value for TCS depends on the jitter of the PLL. Because the PLL is constantly adjusting its output frequency to correspond to the input frequency (from crystal or oscillator), the accumulated jitter is limited. This means that the relative deviation for periods of more than one TCS is lower than for a single TCS (see formulas and **Figure 20**).

This is especially important for bus cycles using waitstates and for the operation of timers, serial interfaces, etc. For all slower operations and longer periods (e.g. pulse train generation or measurement, lower baudrates, etc.) the deviation caused by the PLL jitter is negligible.

The value of the accumulated PLL jitter depends on the number of consecutive VCO output cycles within the respective timeframe. The VCO output clock is divided by the output prescaler K2 to generate the system clock signal f_{SYS}. The number of VCO cycles is K2 × **T**, where **T** is the number of consecutive f_{SYS} cycles (TCS).

The maximum accumulated jitter (long-term jitter) D_{Tmax} is defined by:

D_{Tmax} [ns] = ±(220 / (K2 × f_{SYS}) + 4.3)

This maximum value is applicable, if either the number of clock cycles T > (f_{SYS} / 1.2) or the prescaler value K2 > 17.

In all other cases for a timeframe of **T** × TCS the accumulated jitter D_T is determined by:

D_T [ns] = D_{Tmax} × [(1 - 0.058 × K2) × (T - 1) / (0.83 × f_{SYS} - 1) + 0.058 × K2]

f_{SYS} in [MHz] in all formulas.

Example, for a period of 3 TCSs @ 33 MHz and K2 = 4:

D_{max} = ±(220 / (4 × 33) + 4.3) = 5.97 ns (Not applicable directly in this case!)

D_3 = 5.97 × [(1 - 0.058 × 4) × (3 - 1) / (0.83 × 33 - 1) + 0.058 × 4]
= 5.97 × [0.768 × 2 / 26.39 + 0.232]
= 1.7 ns

Example, for a period of 3 TCSs @ 33 MHz and K2 = 2:

D_{max} = ±(220 / (2 × 33) + 4.3) = 7.63 ns (Not applicable directly in this case!)

D_3 = 7.63 × [(1 - 0.058 × 2) × (3 - 1) / (0.83 × 33 - 1) + 0.058 × 2]
= 7.63 × [0.884 × 2 / 26.39 + 0.116]
= 1.4 ns

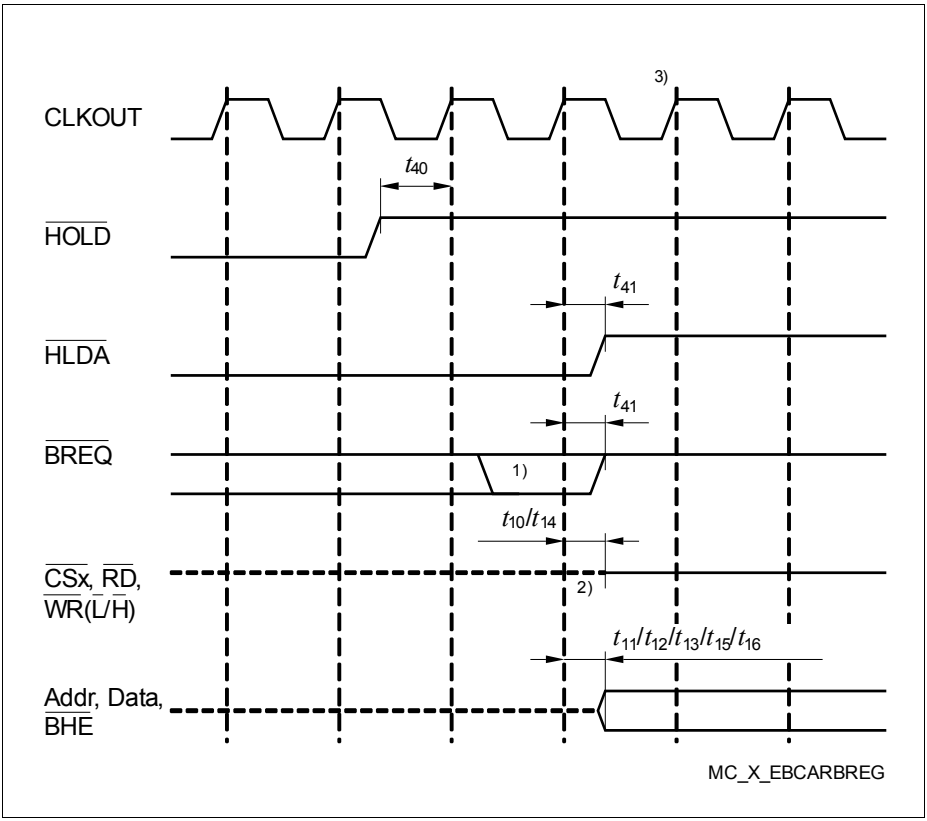

Figure 27 External Bus Arbitration, Regaining the Bus

Notes

1. *This is the last chance for $\overline{BREQ}$ to trigger the indicated regain sequence. Even if $\overline{BREQ}$ is activated earlier, the regain sequence is initiated by $\overline{HOLD}$ going high. Please note that $\overline{HOLD}$ may also be deactivated without the XC238xA requesting the bus.*
2. *The control outputs will be resistive high (pull-up) before being driven inactive (ALE will be low).*
3. *The next XC238xA-driven bus cycle may start here.*

4.6.6 Synchronous Serial Interface Timing

The following parameters are applicable for a USIC channel operated in SSC mode.

Note: These parameters are not subject to production test but verified by design and/or characterization.

Note: Operating Conditions apply; C_L = 20 pF.

Table 34 USIC SSC Master Mode Timing for Upper Voltage Range

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Slave select output SELO active to first SCLKOUT transmit edge	t_1 CC	t_{SYS} - 8 [1]	–	–	ns	
Slave select output SELO inactive after last SCLKOUT receive edge	t_2 CC	t_{SYS} - 6 [1]	–	–	ns	
Data output DOUT valid time	t_3 CC	-6	–	9	ns	
Receive data input setup time to SCLKOUT receive edge	t_4 SR	31	–	–	ns	
Data input DX0 hold time from SCLKOUT receive edge	t_5 SR	-4	–	–	ns	

1) $t_{SYS} = 1 / f_{SYS}$

Table 35 USIC SSC Master Mode Timing for Lower Voltage Range

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Slave select output SELO active to first SCLKOUT transmit edge	t_1 CC	t_{SYS} - 10 [1]	–	–	ns	
Slave select output SELO inactive after last SCLKOUT receive edge	t_2 CC	t_{SYS} - 9 [1]	–	–	ns	
Data output DOUT valid time	t_3 CC	-7	–	11	ns	